

Abstract of the Disclosure:

A stacked semiconductor package comprises two semiconductor chips (11, 12) each of which has a mounting surface provided with a plurality of chip pins arranged in a predetermined pattern. The semiconductor chips are mounted on opposite surfaces of a substrate (13) so that the mounting surfaces are faced to each other through the substrate. The substrate is provided with a plurality of package pins formed in an area other than a chip mounting area and arranged in a pattern identical to the predetermined pattern. A pair of the corresponding chip pins of the semiconductor chips are connected to a via formed at an intermediate position therebetween by the use of branch wires equal in length to each other. The via is connected by a common wire to the package pin corresponding to the chip pins connected to the via.